

FEATURES

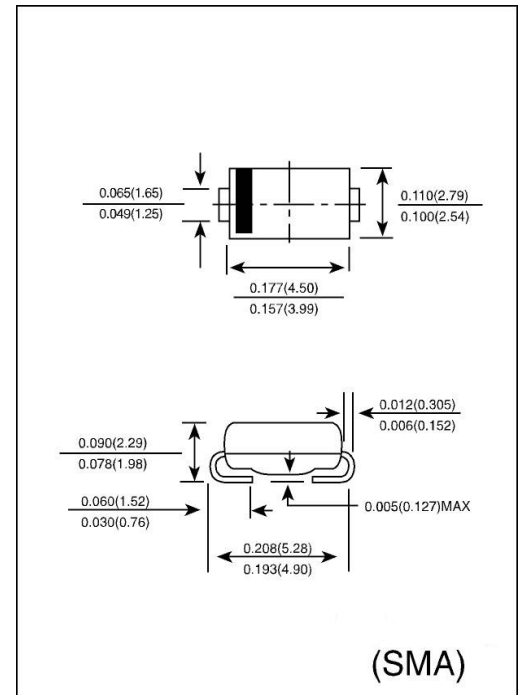
- Glass passivated chip junction
- Ideal for surface mounted applications
- Low leakage
- High forward surge current capability.
- High temperature soldering guaranteed:
260°C/10 seconds at terminals.

MECHANICAL DATA

- Case: Transfer molded plastic
- Epoxy: UL94V - 0 rate flame retardant.
- Polarity: Color band denotes cathode end
- Lead: Plated terminals solderable per MIL - STD - 202E
method 208C
- Weight: 0.002 ounce, 0.057 gram

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

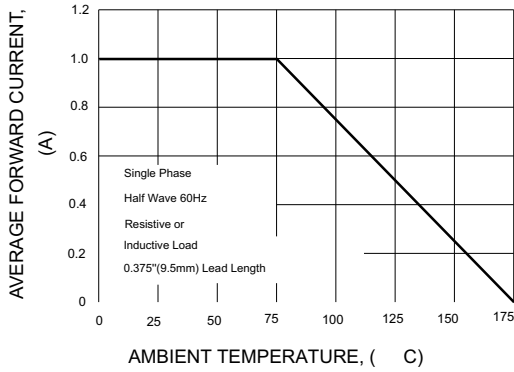
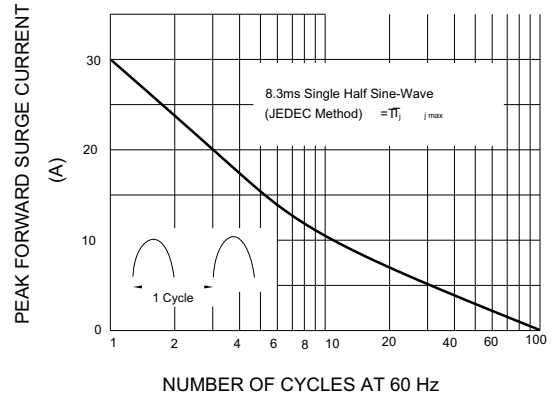
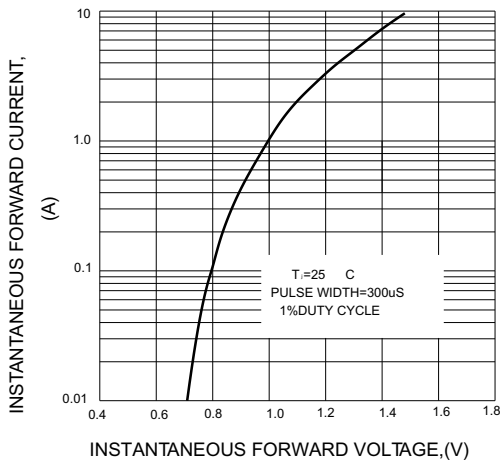
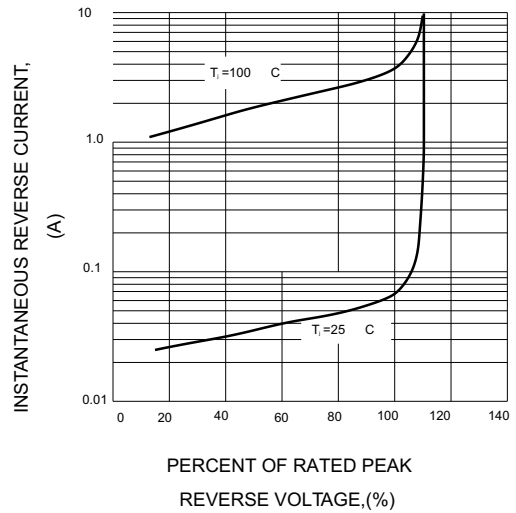
- Ratings at 25°C ambient temperature unless otherwise specified
- Single phase, half wave, 60Hz, resistive or inductive load.
- For capacitive load derate current by 20%



CatalogNumber	SYMBOLS	M7	UNITS
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	Volts
Maximum RMS Voltage	V_{RMS}	700	Volts
Maximum DC Blocking Voltage	V_{DC}	1000	Volts
Maximum Average Forward Rectified Current, at $T_A = 75^\circ C$	$I_{(AV)}$	1.0	Amp
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30	Amps
Maximum Instantaneous Forward Voltage Drop at 1.0A	V_F	1.1	Volts
Maximum DC Reverse Current at rated DC blocking voltage	I_R	$T_C = 25^\circ C$	5.0
		$T_A = 125^\circ C$	50
Maximum Full Load Reverse Current, full cycle average at $T_A = 75^\circ C$	$I_{R(AV)}$	30	μA
Typical Junction Capacitance (Note 1)	C_J	15	pF
Typical Thermal Resistane (Note 2)	$R_{\theta JA}$	75	$^\circ C/w$
Operating and Storage Temperature Range	T_J, T_{STG}	(-65 to +175)	$^\circ C$

NOTES:

1. Measured at 1.0 MHz and applied average voltage of 4.0 volts.
2. 6.0 X 6.0mm² copper pads to each terminal.

**FIG.1-TYPICAL FORWARD CURRENT
DERATING CURVE**

**FIG.2-MAXIMUM NON-REPETITIVE PEAK
FORWARD SURGE CURRENT**

**FIG.3-TYPICAL INSTANTANEOUS
FORWARD CHARACTERISTICS**

**FIG.4-TYPICAL REVERSE
CHARACTERISTICS**

FIG.5-TYPICAL JUNCTION CAPACITANCE
